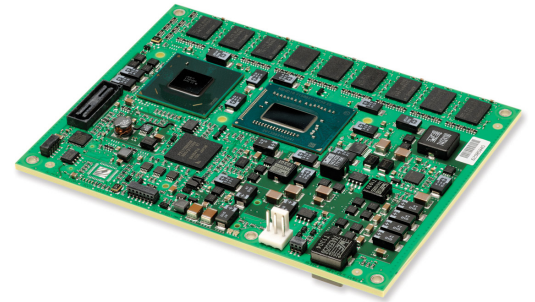




bCOM6-L1400

Rugged COM Express®



GE understands that long design cycles and high validation costs make it difficult for OEMs to keep up with the latest processor technologies. We also know that processors deployed in harsh environments need to deliver the utmost performance at all times, under any condition.

To address these needs, GE developed the bCOM6-L1400. This module takes advantage of the significantly enhanced video processing, turbo-boost acceleration and power management capabilities of the latest generation Intel® Core™ i7 processor. As such, the bCOM6-L1400 is ideally suited for a wide variety of commercial, industrial, transportation and defense applications in a broad range of embedded computing environments. This durable COM Express solution reduces overall design cycle and validation costs to lower total cost of ownership.

Best-in-class performance and reliability

GE's bCOM6-L1400 is the premium solution in our COM Express portfolio. It offers the high-level performance and ultimate durability needed for applications that operate in harsh environments. The bCOM6-L1400 should be selected for applications with multiple graphic functions or high-end computing needs. All GE Type 6 modules fully use the capabilities of the newest generation of processors.

Onboard components are specifically selected for their reliability in demanding conditions. Unlike solutions designed for benign environments, our processor and memory are soldered to the board for maximum resistance to shock and vibration. Extended mechanical construction protects the module, which is designed for optional conformal coating for even greater resistance to moisture, dust, chemicals, and temperature extremes.

Longer lifecycles and lower product costs

COM Express architecture separates the processor and carrier card. This extends the useful life of the subsystem by allowing a simple, cost-effective upgrade of the processor alone. The long-term cost of ownership is reduced while ensuring that performance keeps pace with changing needs.

Commitment to customer satisfaction

Today's organizations are operating lean, engineering resources are scarce, and time-to-market is critical. Therefore, GE complements the performance and practical benefits of our COM Express modules with world-class domain expertise and a focus on exceptional customer service. To help you get to market faster and lower your development costs, we can assist you with in-house carrier design work, or build a custom carrier specifically for you.

FEATURE	BENEFIT
Rugged design with soldered components	<ul style="list-style-type: none"> • Reliable computing capabilities for applications needing higher immunity to shock and vibration
Next-generation multicore Intel Core i7 processors	<ul style="list-style-type: none"> • Delivers high performance coupled with low power consumption • Supports multiple graphics displays
Dynamic thermal management	<ul style="list-style-type: none"> • Enables controlled system shutdown to avoid damage to equipment • Offers cost saving by allowing simulation in the lab before conducting field tests
Flexible options	<ul style="list-style-type: none"> • Additional shock and vibration protection

